2SD2413

Silicon NPN triple diffusion planar type

For low-frequency output amplification

■ Features

- High collector-base voltage (Emitter open) V_{CBO}
- High collector-emitter voltage (Base open) V_{CEO}
- Large collector power dissipation P_C
- Low collector-emitter saturation voltage V_{CE(sat)}
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	400	V
Collector-emitter voltage (Base open)	V _{CEO}	400	V
Emitter-base voltage (Collector open)	V _{EBO}	5	V
Collector current	$I_{\rm C}$	100	mA
Peak collector current	I_{CP}	200	mA
Collector power dissipation *	$P_{\rm C}$	1	W
Junction temperature	Tj	150	°C
Storage temperature	$T_{\rm stg}$	-55 to +150	°C

Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

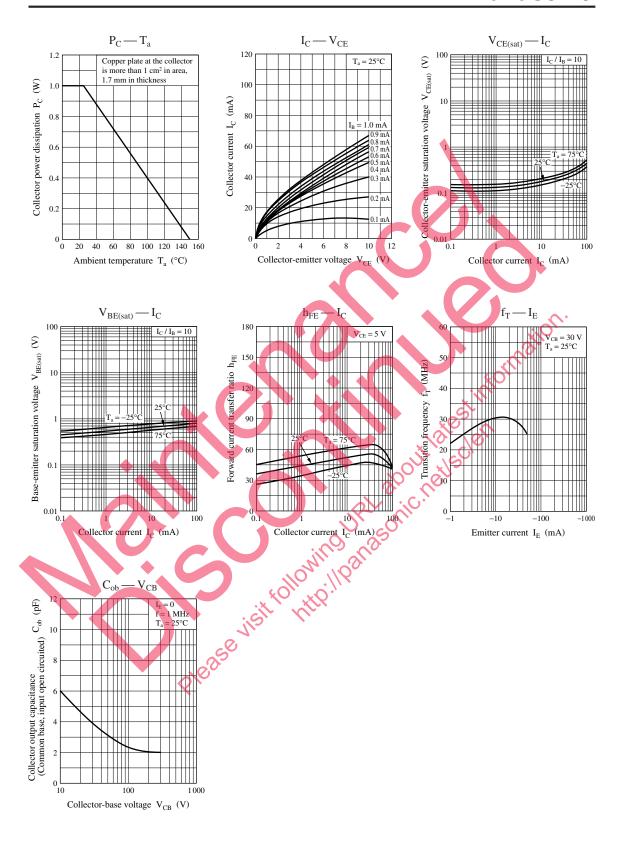
Unit: mm 4.5±0. 1.5±0.1 Marking Symbol: 1S W OC OC And the Anasonic.net/sclen 2 : Collector 3: Emitter MiniP3-F1 Package

■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 100 \mu A J_E = 0$	400			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 500 \mu \text{A}, I_{\rm B} = 0$	400			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 100 \mu\text{A}, I_C = 0$	5			V
Forward current transfer ratio	ch_{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 30 \text{ mA}$	30			_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$			1.5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$			1.5	V
Transition frequency *	f_T	$V_{CB} = 30 \text{ V}, I_E = -20 \text{ mA}, f = 200 \text{ MHz}$		40		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 30 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$			7	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Pulse measurement



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